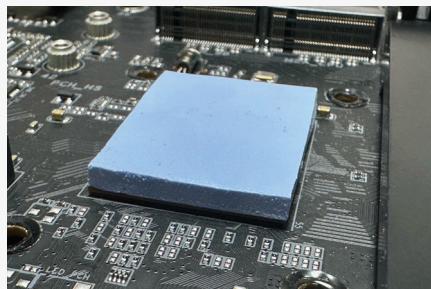


Thermal Pad BDA-2030



Features

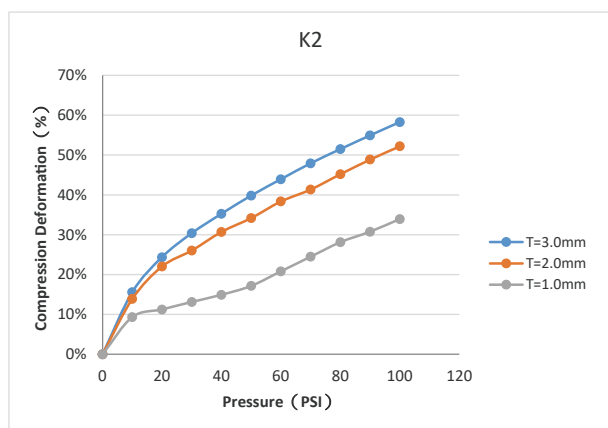
- Thermal Conductivity :2.0W/m·K
- Excellent flame retardancy
- Good Compressibility and Elasticity
- Good electrical insulation performance
- Easy For Installation

Applications

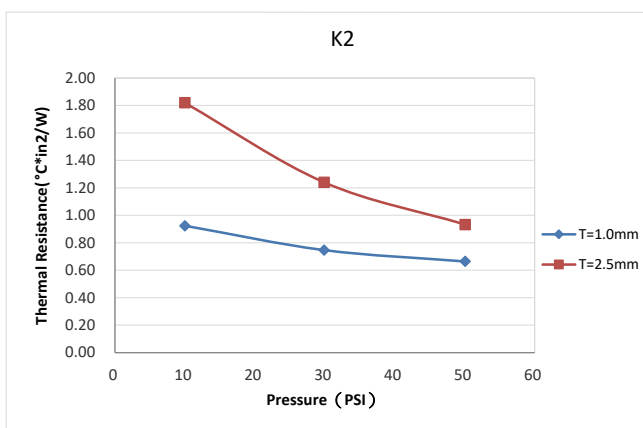
- Communication hardware
- Memory Modules
- Mass Storage Devices
- Automotive Electronics
- Smartphones
- Semiconductor heat sink

BDA -2030 thermal pad conductive silicone sheet is used to fill the interface of two objects, so that the air from the interface is discharged and the thermal conductivity is improved. The product has self-adhesive, can be die-cut into a variety of shapes, easy assembly. The thermal conductivity is 2.0 W/m. K

■ Compression Ratio



■ Thermal Resistance VS Pressure



Parameter

Project	Thermal Pad BDA-2030	Test Method
Thermal Conductivity(W/m·K)	2.0	ASTM D5470
Operating Temperature (°C)	-50~200	—
Color	TBA	Visual
Density (g/cm ³)	2.7	ASTM D792
Thickness Range (mm)	0.5~5.0	ASTM D374
Thickness Tolerance> 1mm	±10%mm	—
Hardness (Shore 00)	20~60	ASTM D2240
Breakdown Voltage (KV AC/mm)	>7	ASTM D149
Volume Resistivity (Ohm·cm)	10 ¹³	ASTM D257
Dielectric Constant@1MHz	>6	ASTM D150
UL Flammability Rating	V0	UL 94
ROHS/HF/REACH	PASS	—

Storage in shade, Storage temperature: ≤30 °C, Storage humidity: ≤70%
12 months from the date of manufacture